

FIG. 1A

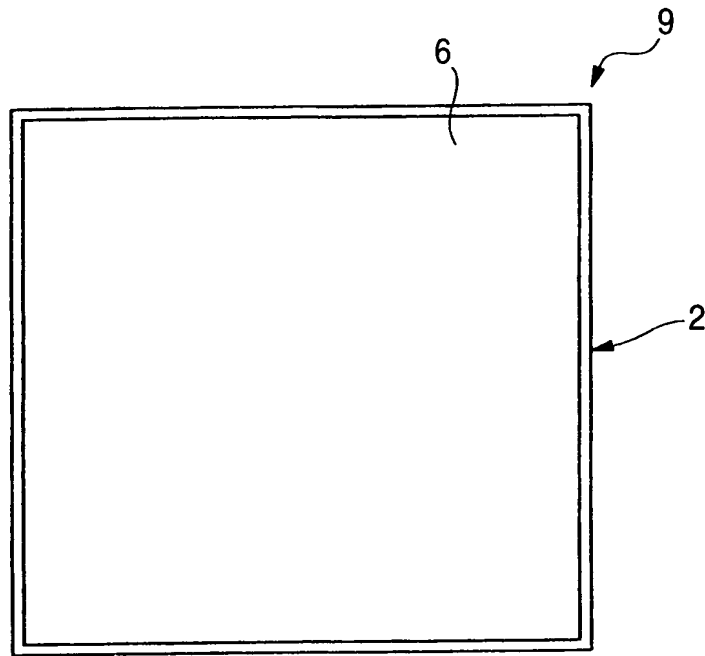
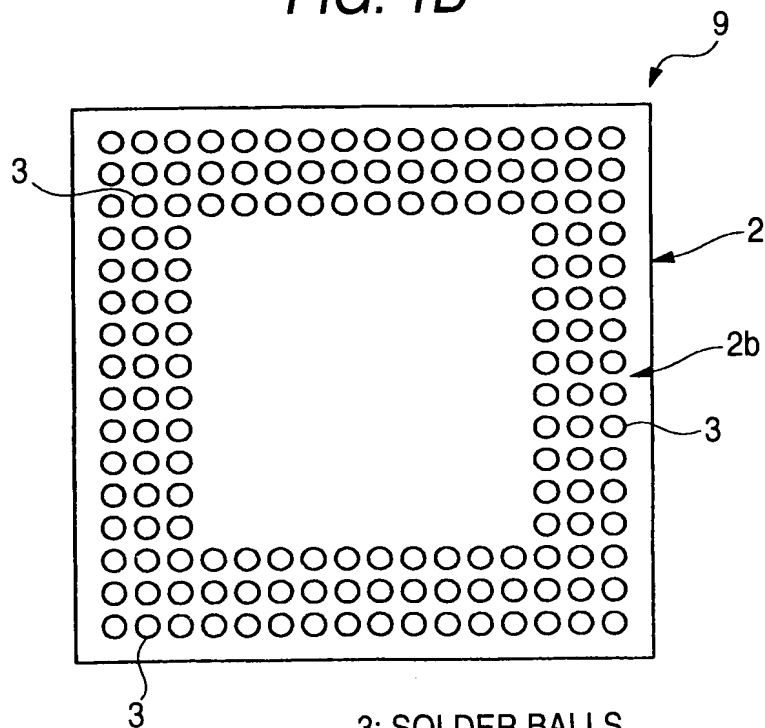
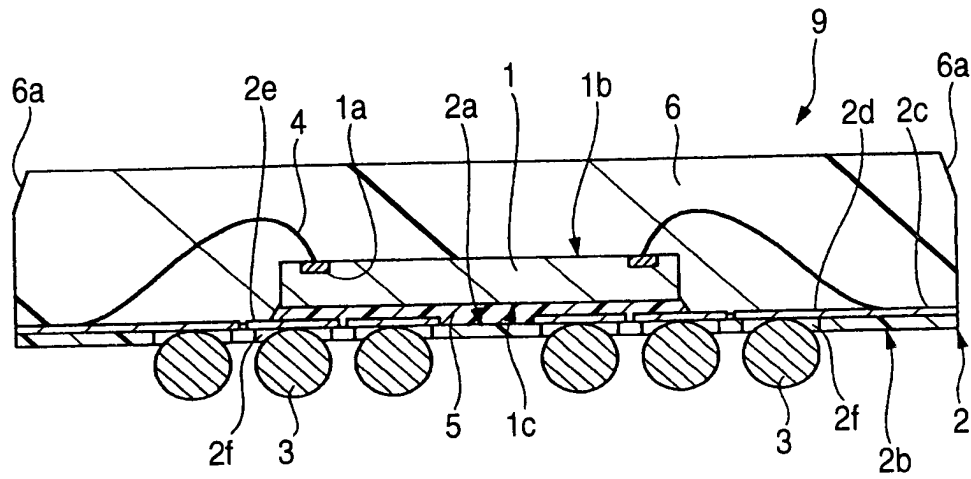


FIG. 1B



3: SOLDER BALLS  
 6: SEALED PORTION  
 9: CSP (SEMICONDUCTOR DEVICE)

FIG. 2



1a: PADS (SURFACE ELECTRODES)  
 2c: CONNECTION TERMINALS (ELECTRODES)

FIG. 3A

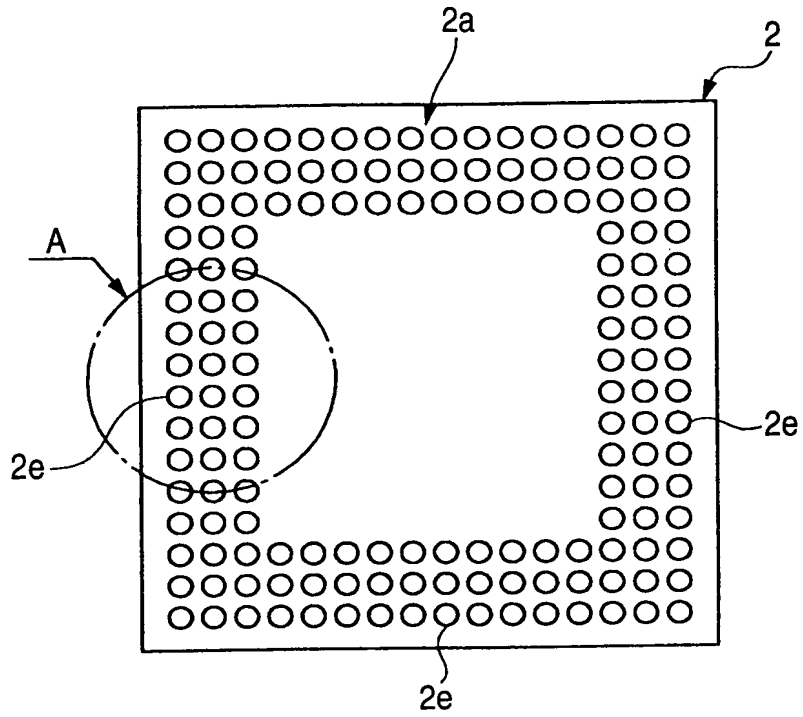


FIG. 3B

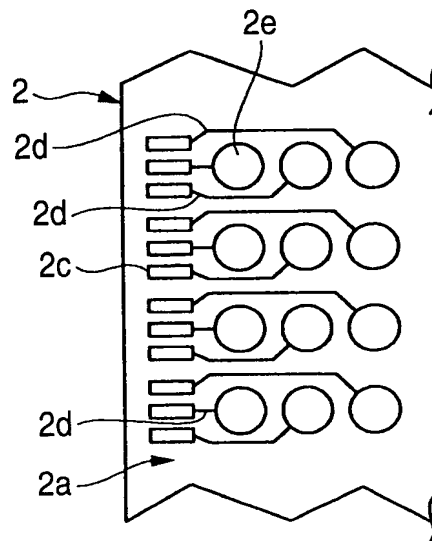
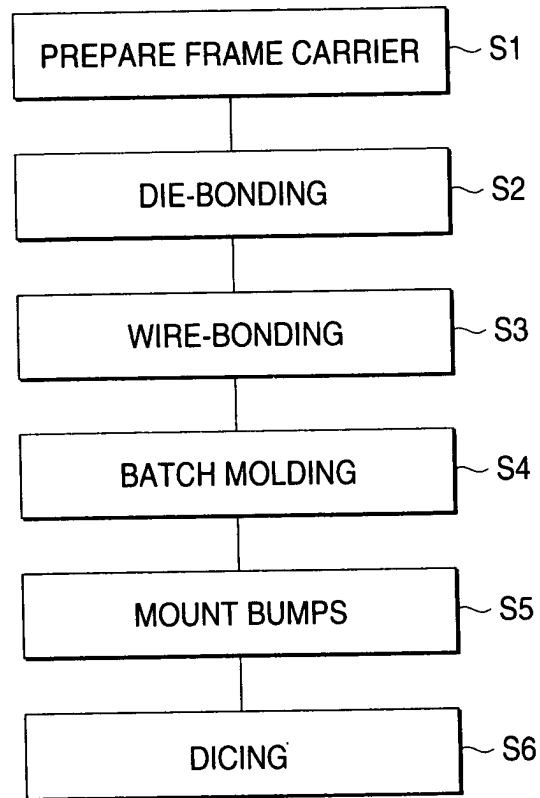
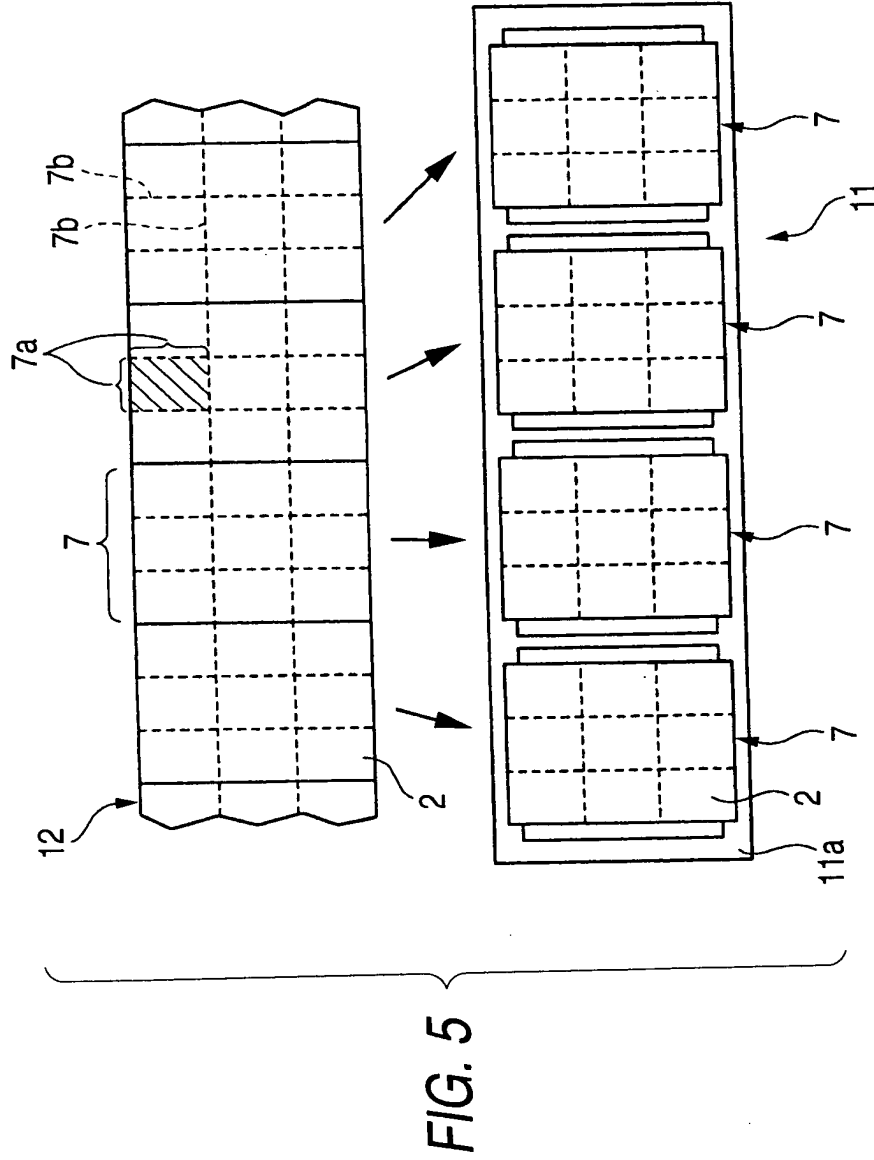


FIG. 4



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- 7a: DEVICE AREA
- 7b: DICING LINES
- 11: FRAME CARRIER
- 11a: FRAME MEMBER

**FIG. 6**

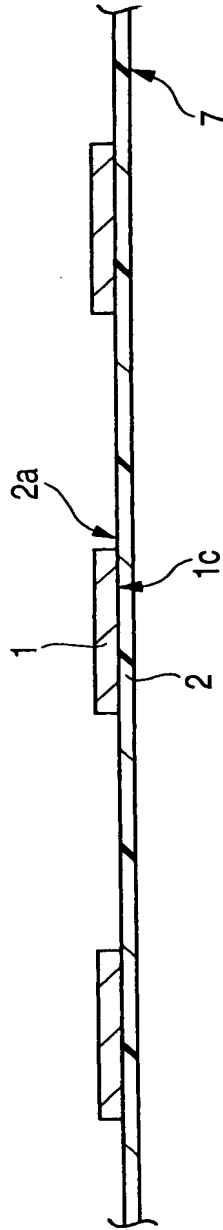
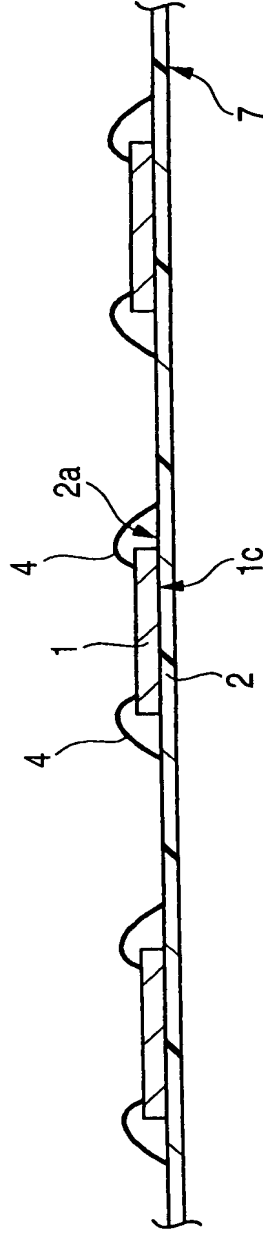


FIG. 7



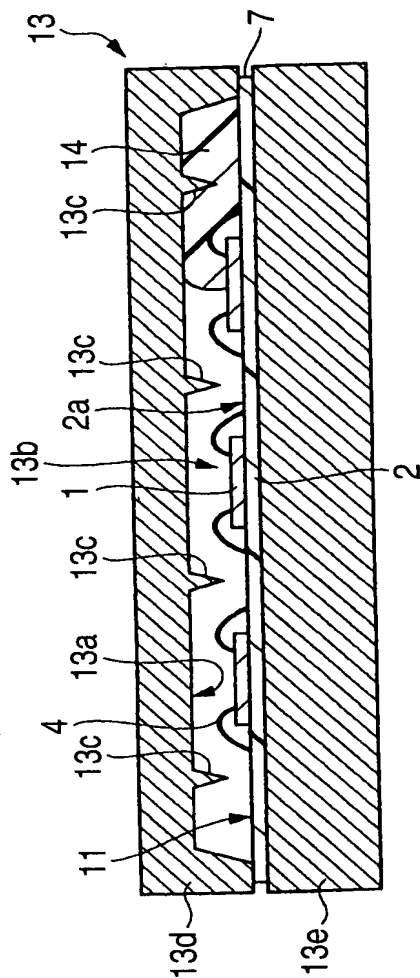
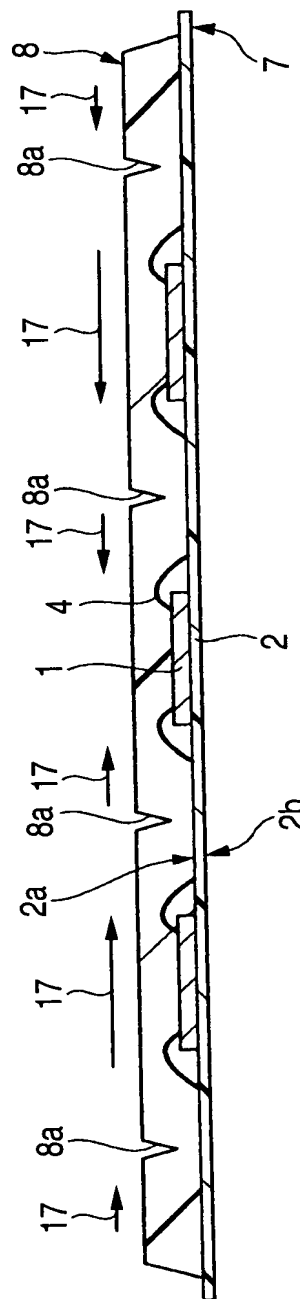


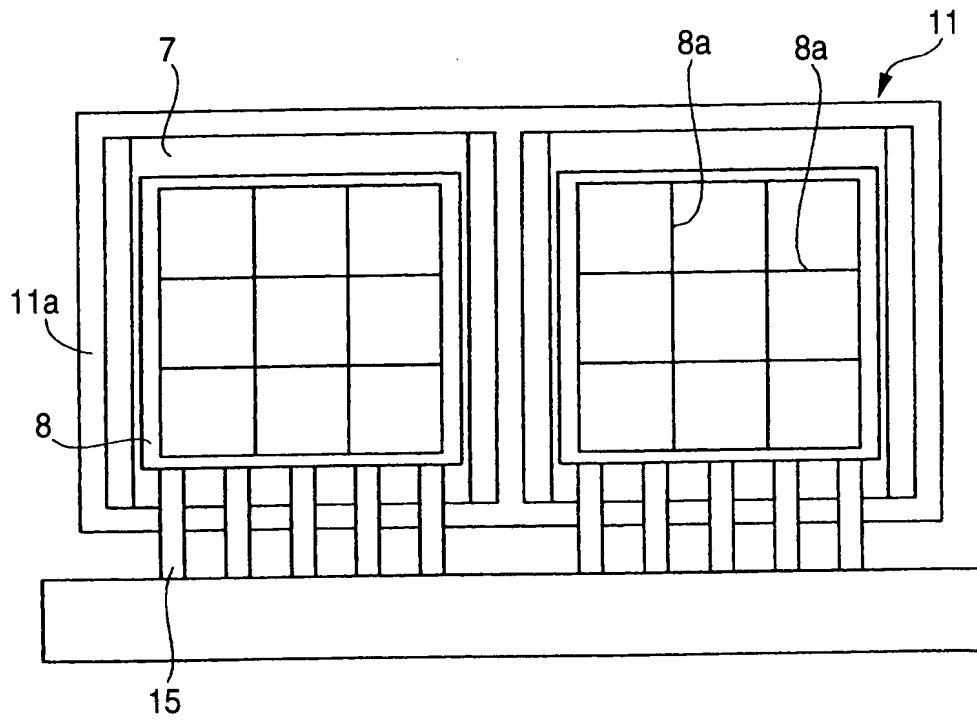
FIG. 8A

FIG. 8B



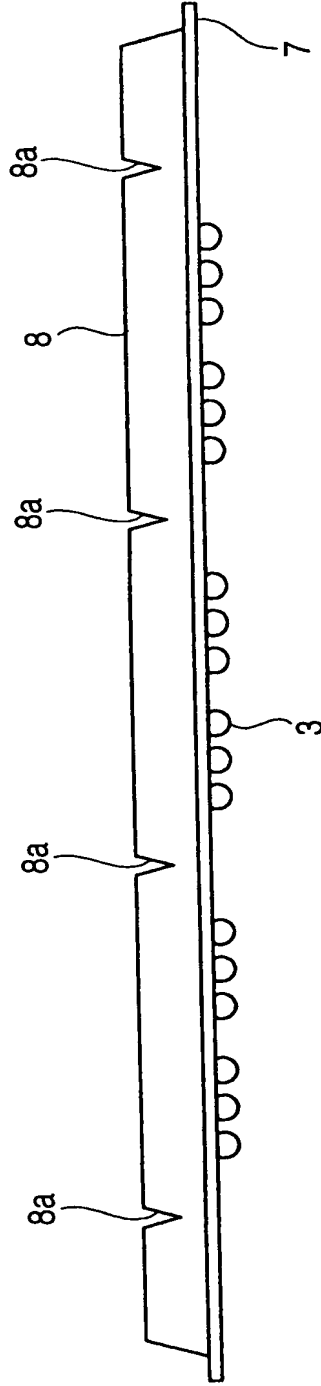
- 1: SEMICONDUCTOR CHIP
- 2: TAPE SUBSTRATE
- 2a: CHIP SUPPORTING SUBSTRATE
- 2b: BACK FACE (OPPOSITE FACE)
- 4: WIRES (CONDUCTIVE MEMBERS)
- 7: MULTI-DEVICE SUBSTRATE
- 8: BLOCK-MOLDED PORTION (BATCH-SEALED PORTION)
- 8a: GROOVES
- 13: MOLDING TOOL
- 13a: CAVITY FORMING FACE
- 13b: CAVITY
- 13c: PROTRUSIONS
- 14: MOLDING RESIN

FIG. 9

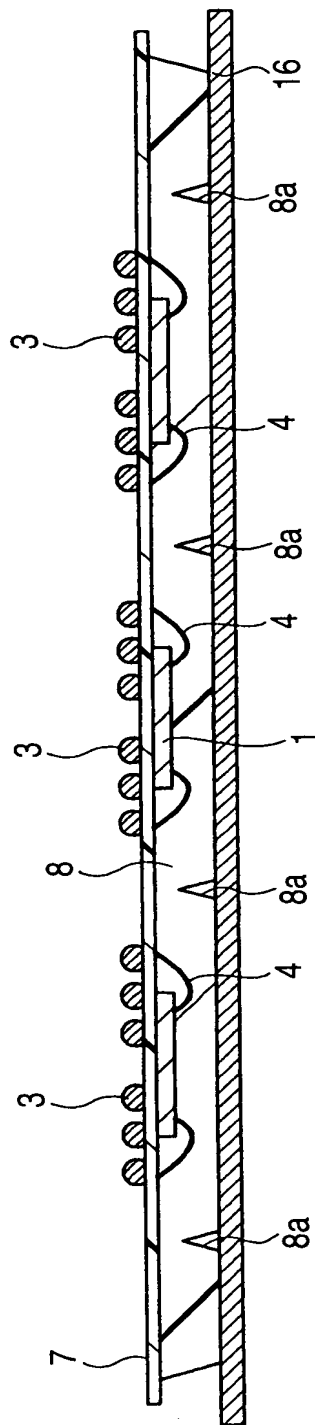


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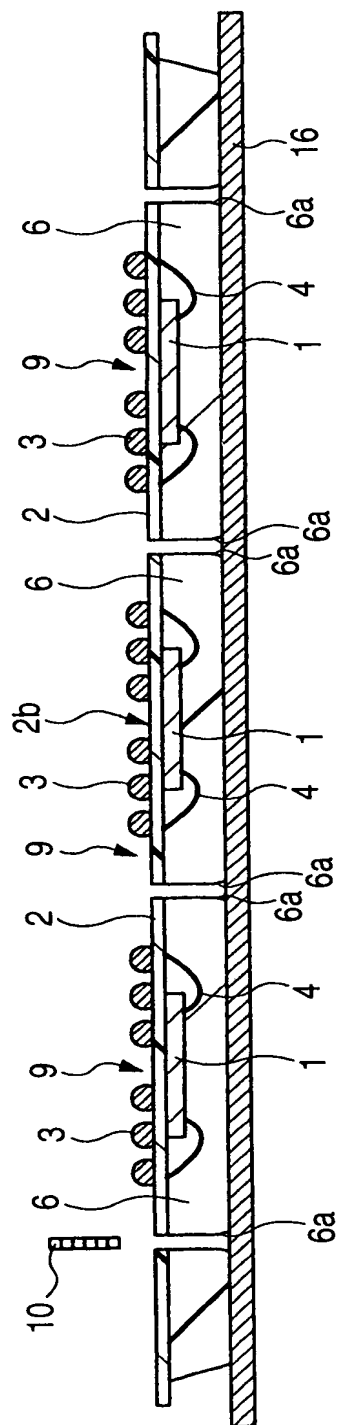
FIG. 10



**FIG. 11A**



**FIG. 11B**



## 10: BLADE



FIG. 13

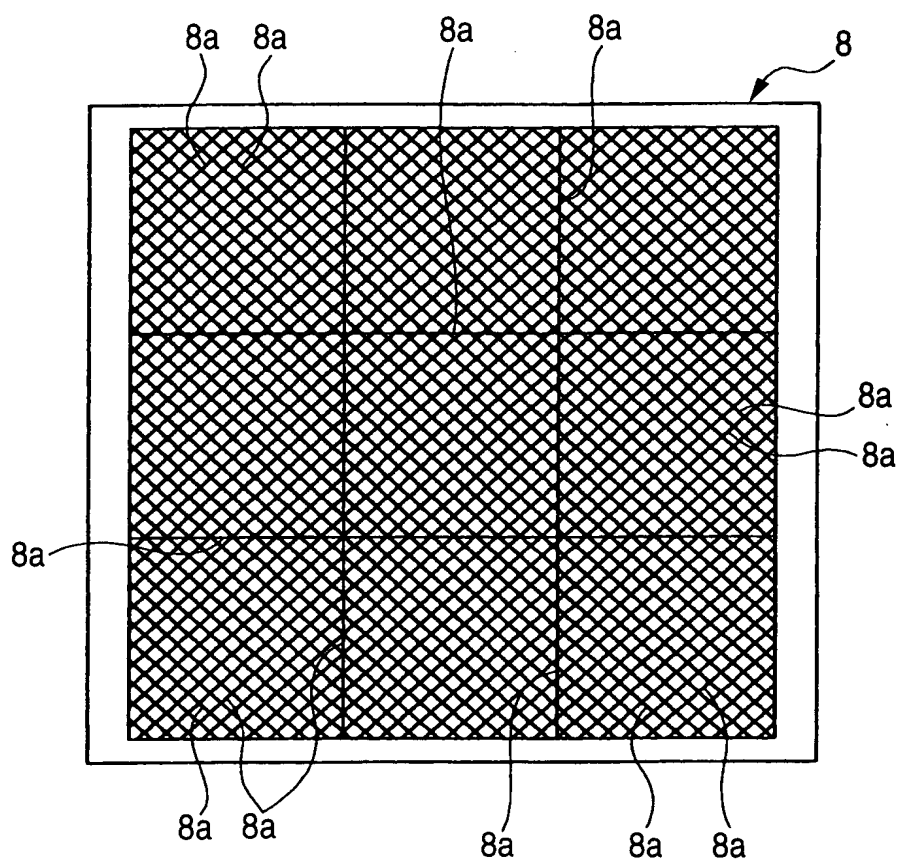
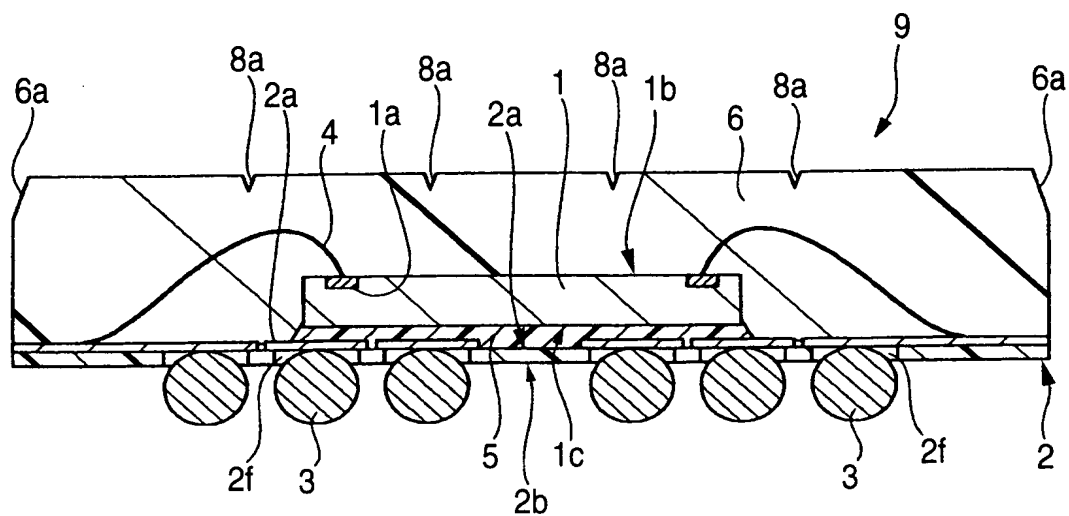
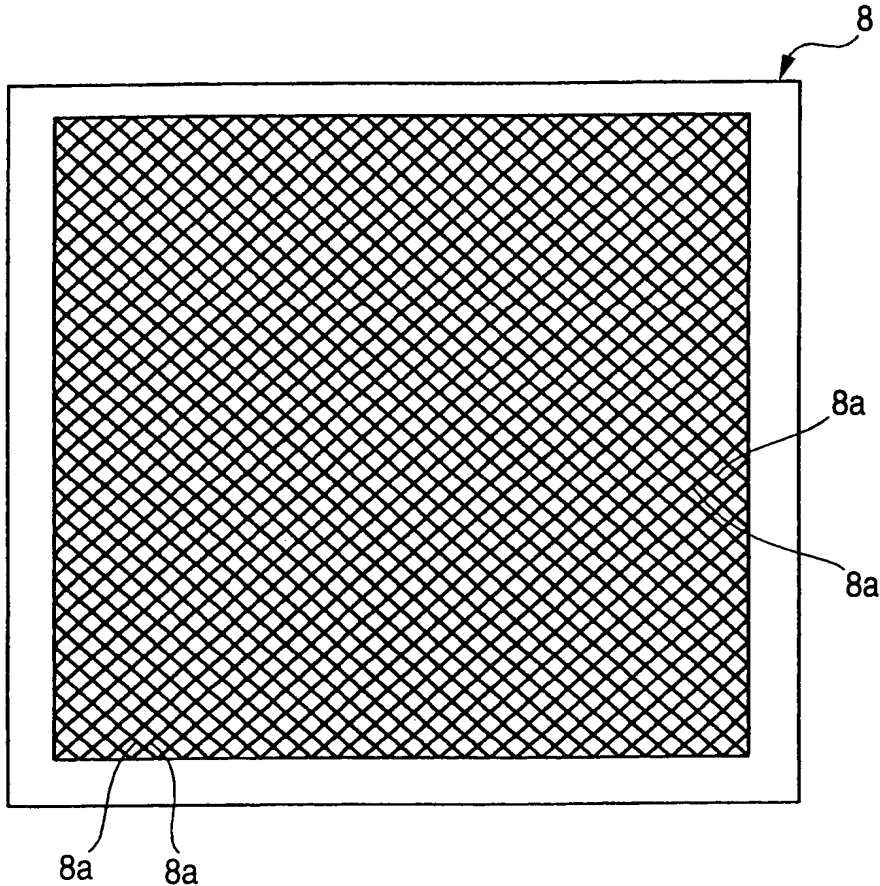


FIG. 14



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FIG. 15



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FIG. 16

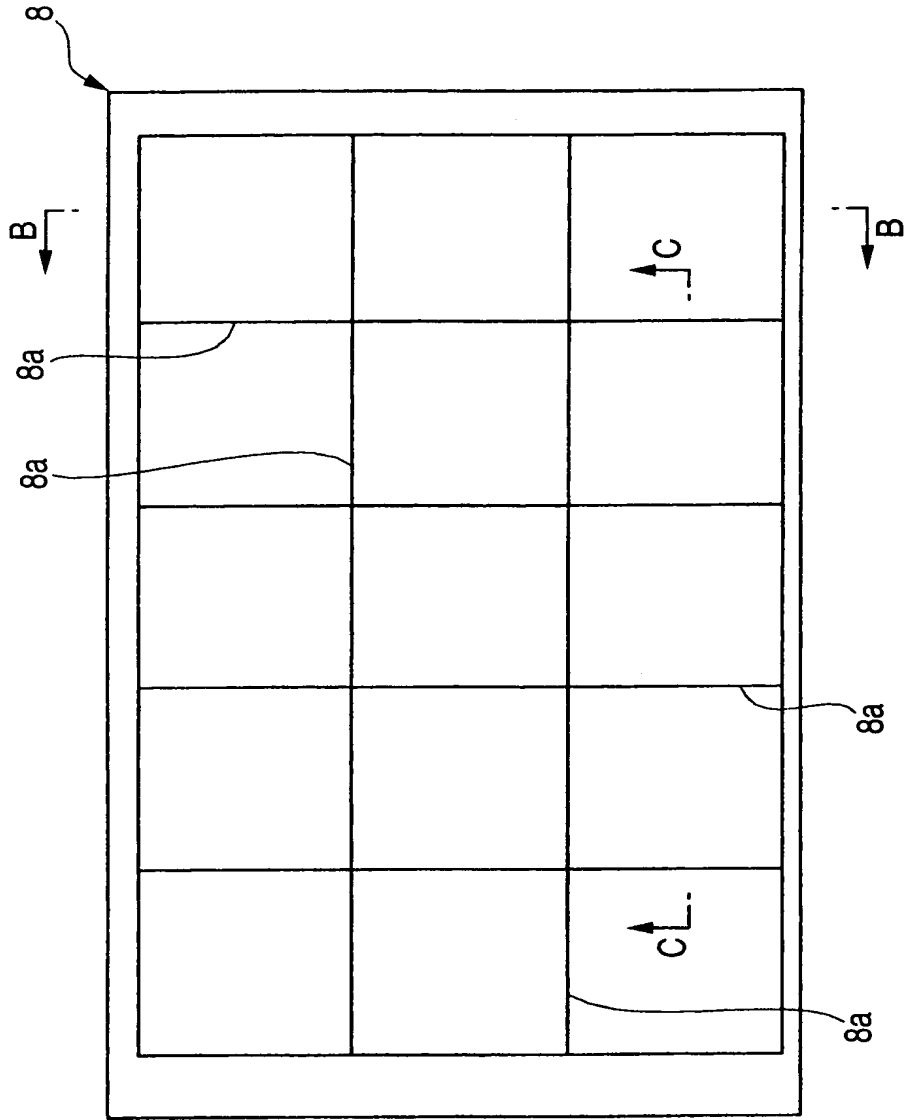


FIG. 17A

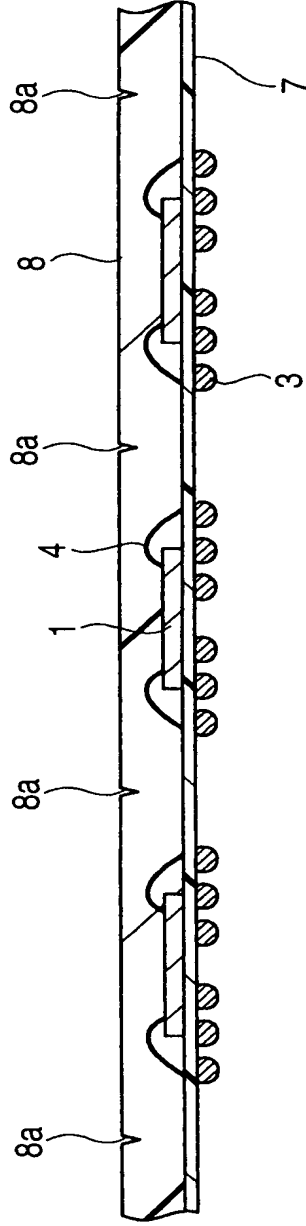


FIG. 17B

